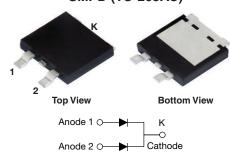


# Hyperfast Rectifier, 2 x 15 A FRED Pt®

## eSMP<sup>®</sup> Series SMPD (TO-263AC)



### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2 x 15 A			
V <sub>R</sub>	600 V			
V <sub>F</sub> at I <sub>F</sub> (T <sub>J</sub> = 150 °C)	1.22 V			
t <sub>rr</sub>	30 ns			
T <sub>J</sub> max.	175 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Common cathode			

#### **FEATURES**

- Hyperfast recovery time, reduced Q<sub>rr</sub>, and soft recovery
- 175 °C maximum operating junction temperature



- For PFC CRM, snubber operation
- · Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and ultrafast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in PFC, boost, lighting, in the AC/DC section of SMPS, freewheeling and clamp diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element and snubbers.

#### **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage		$V_{RRM}$		600	V
Account we stiffed from and account	per device	I <sub>F(AV)</sub> (1)	T <sub>C</sub> = 130 °C	30	
Average rectified forward current	per diode			15	Α
Non-repetitive peak surge current, per diode		I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 10 ms sine pulse	160	

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_{R}$	I <sub>R</sub> = 100 μA	600	-	-	
Forward voltage, per diode	V <sub>F</sub>	I <sub>F</sub> = 15 A	-	1.63	2.15	V
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 150 °C	-	1.22	1.65	
Reverse leakage current, per diode	I <sub>R</sub>	$V_R = V_R$ rated	-	-	20	μА
		$T_J = 150  ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	-	500	
Junction capacitance, per diode	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	16	-	pF

#### Note

(1) Mounted on infinite heatsink



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	30	-	
Reverse recovery time per diode	t <sub>rr</sub>	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr} = 0.25 \text{ A}$		-	-	30	1
		T <sub>J</sub> = 25 °C	I <sub>F</sub> = 15 A, dI <sub>F</sub> /dt = 500 A/μs, V <sub>R</sub> = 400 V	-	41	-	ns
		T <sub>J</sub> = 125 °C		-	92	-	
Peak recovery current per diode	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	7	-	_
		T <sub>J</sub> = 125 °C		-	13	-	A
Doverno recovery charge ner diede	0	T <sub>J</sub> = 25 °C		-	150	-	nC
Reverse recovery charge per diode	diode Q <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	590	-	110

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	+175	°C
Thermal resistance, junction to mount, per diode	R <sub>thJM</sub>		-	1.2	1.7	°C/W
Approximate weight				0.55	•	g
Approximate weight				0.02		OZ.
Marking device		Case style SMPD (TO-263AC)		30CI	DH06	

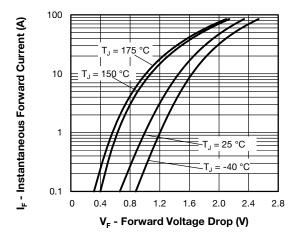


Fig. 1 - Typical Forward Voltage Drop Characteristics, Per Diode

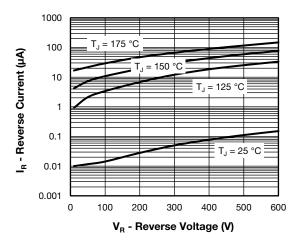


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage, Per Diode

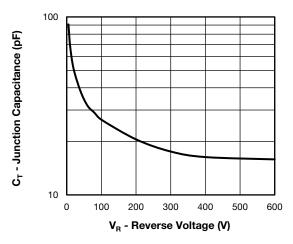


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, Per Diode

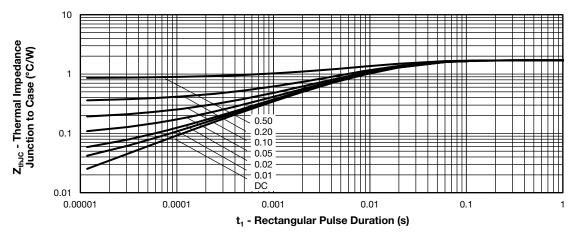


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics, Per Diode

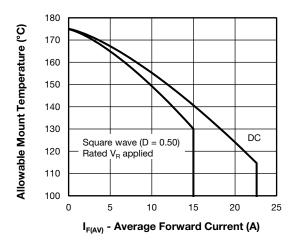


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current, Per Diode

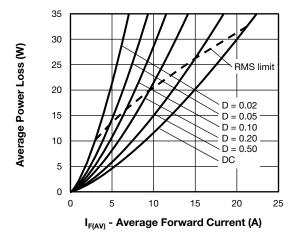


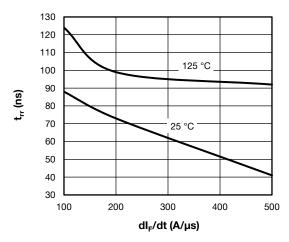
Fig. 6 - Forward Power Loss Characteristics, Per Diode

### Note

Formula used: T<sub>C</sub> = T<sub>J</sub> - (Pd + Pd<sub>REV</sub>) x R<sub>th,JC</sub>; Pd = forward power loss = I<sub>F(AV)</sub> x V<sub>FM</sub> at (I<sub>F(AV)</sub>/D) (see fig. 5); Pd<sub>REV</sub> = inverse power loss = V<sub>R1</sub> x I<sub>R</sub> (1 - D); I<sub>R</sub> at V<sub>R1</sub> = rated V<sub>R</sub>

### www.vishay.com

# Vishay Semiconductors



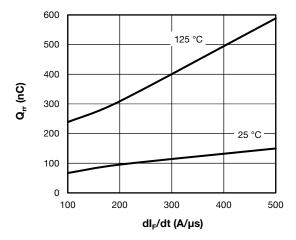
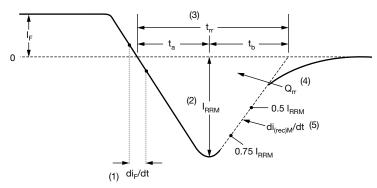


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt, Per Diode

Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt, Per Diode



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $I_{F}$  to point where a line passing through 0.75  $I_{RRM}$  and 0.50  $I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

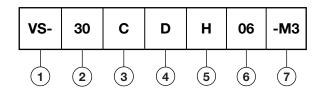
(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 9 - Reverse Recovery Waveform and Definitions



### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Current rating (30 A)

**3** - Circuit configuration:

C = common cathode

4 - D = SMPD package

5 - Process type,

H = hyperfast recovery

6 - Voltage code (06 = 600 V)

7 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

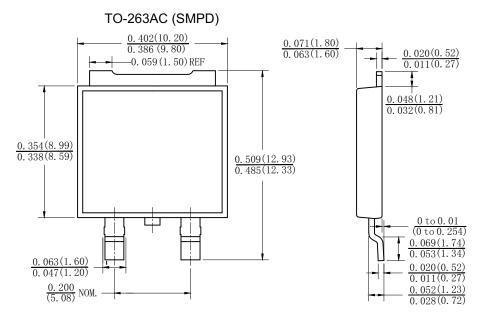
ORDERING INFORMATION (Example)						
PREFERRED P/N QUANTITY PER REEL MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION						
VS-30CDH06-M3/I	2000	2000	13" diameter plastic tape and reel			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95604			
Part marking information	www.vishay.com/doc?95566			
Packaging information	www.vishay.com/doc?88869			
SPICE model	www.vishay.com/doc?96776			

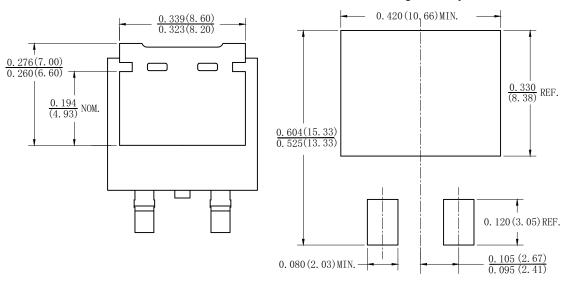


# TO-263AC (SMPD)

### **DIMENSIONS** in inches (millimeters)



### Mounting Pad Layout





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